SPECIFICATION

Part No.	:	**PA.22A**
Product Name	:	Tri-band Cellular Dielectric PIFA Antenna
Description	:	Tri-band Cellular 800/1800/1990 MHz 0dB Gain Size: 29.8mm*6mm*5mm RoHS Compliant

1. Introduction

This specification is for a Tri-band GSM miniature PIFA (Dielectric Planar Inverted-F Type Antenna) (DPA™) Antenna for internal SMT mounting.

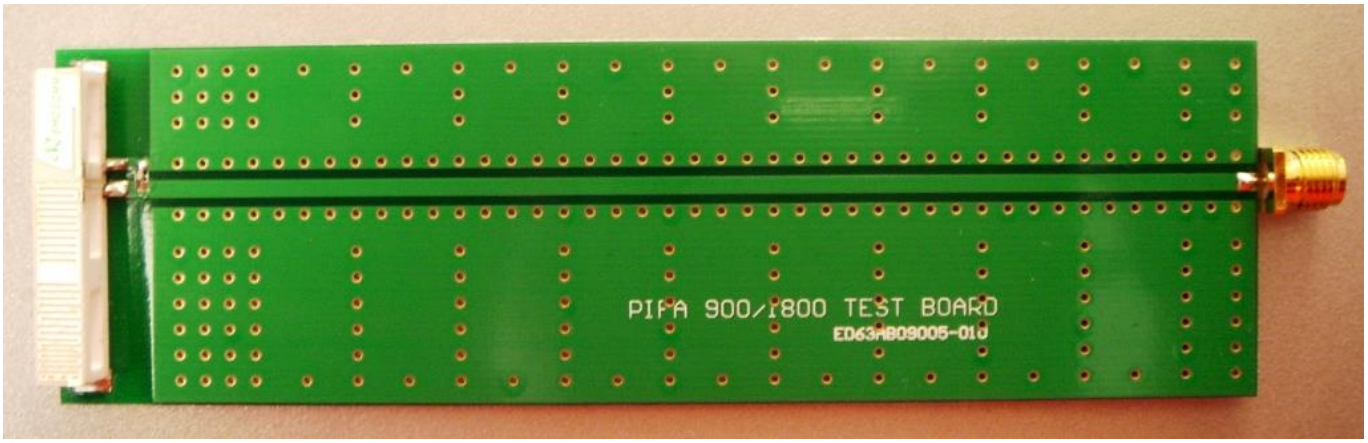
Note: The antenna also shows a response at 850MHz which means the antenna can also be defined on quad-band, depending on the target specification for the device itself.

2. Specifications

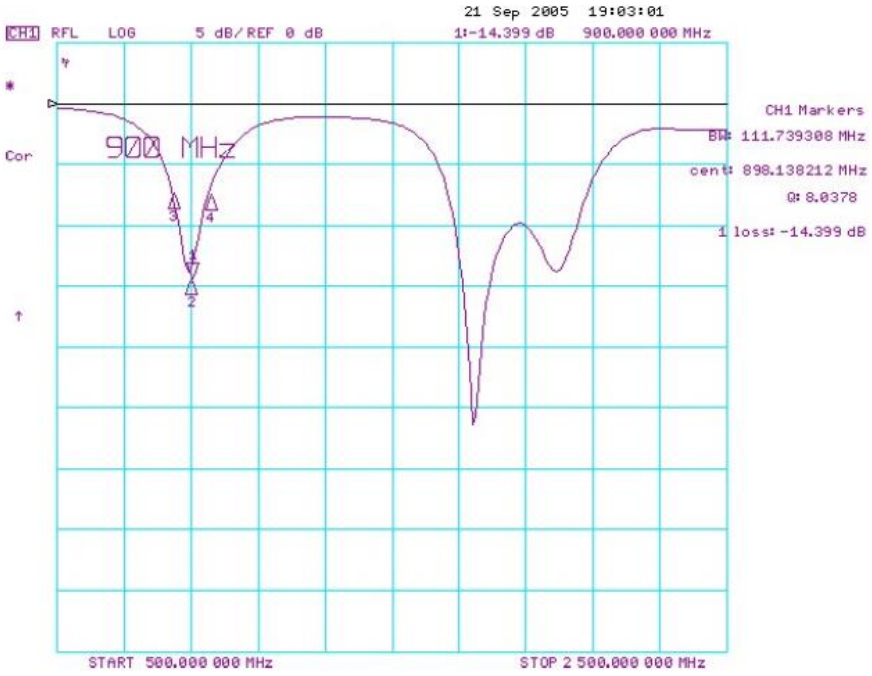
The antenna has the electrical characteristics given in Table 1 under the Taoglas standard installation conditions as shown in the Evaluation Board (Figure

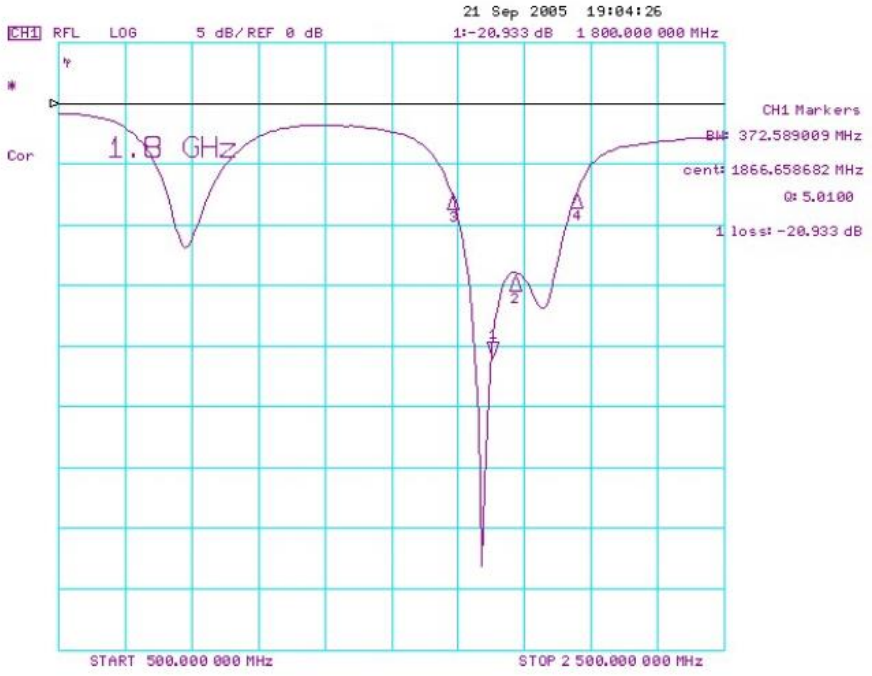
Specification	
Frequency	880~960 MHz, 1710~1990 MHz
Dimensions	29.8*6.0*5.0 mm
Impedance	50 Ω
VSWR	2.5 max (depends on environment)
Polarization	Linear
Operating Temperature	-40~85°C
Termination	Ag (Environmentally Friendly Lead- Free)

*Data is measured on Taoglas Evaluation Board (reference ground plane) pictured below



2.1. S11 Response Curve





Radiation patterns also available (measured in free space and on evaluation board)

2.2 Gain and Efficiency

GSM900

Frequency (MHz)		Peak Gain (dBi)	Efficiency (%)
TX	880.2	-3.65	21.09
	890.2	-2.73	26.25
	902.4	-2.28	31.23
	914.8	-2.04	35.24
RX	925.2	-1.96	37.02
	935.2	-2.54	33.33
	947.4	-2.96	31.17
	959.8	-3.16	29.47

GSM900

Frequency (GHz)		Plane	Average Gain (dBi)
TX	880.2	XY plane	-7.133
		YZ plane	-9.766
		XZ plane	-6.101
	890.2	XY plane	-5.968
		YZ plane	-8.845
		XZ plane	-5.126
	902.4	XY plane	-4.898
		YZ plane	-8.892
		XZ plane	-4.350
	914.8	XY plane	-4.077
		YZ plane	-7.477
		XZ plane	-3.865
RX	925.2	XY plane	-3.599
		YZ plane	-7.202
		XZ plane	-3.732
	935.2	XY plane	-3.802
		YZ plane	-7.648
		XZ plane	-4.290
	947.4	XY plane	-3.788
		YZ plane	-7.843
		XZ plane	-4.579
	959.8	XY plane	-3.801
		YZ plane	-7.913
		XZ plane	-5.187

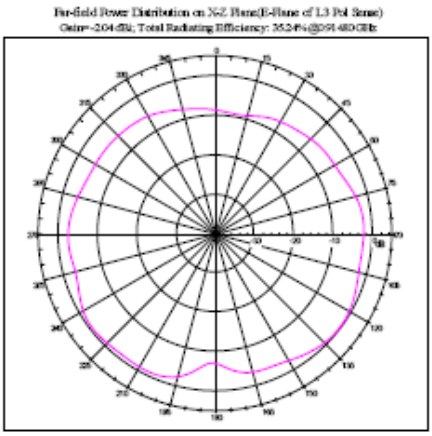
GSM1800

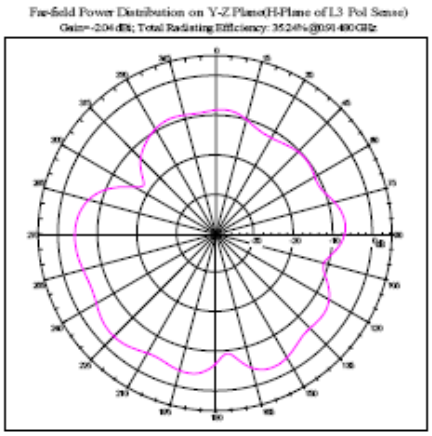
Frequency (GHz)		Plane	Average Gain (dBi)
TX	1710.2	XY plane	-2.648
		YZ plane	-4.661
		XZ plane	-1.687
	1747.6	XY plane	-2.529
		YZ plane	-4.696
		XZ plane	-1.207
	1784.8	XY plane	-2.685
		YZ plane	-4.687
		XZ plane	-0.888
RX	1805.2	XY plane	-3.193
		YZ plane	-4.911
		XZ plane	-1.105
	1842.6	XY plane	-3.468
		YZ plane	-4.753
		XZ plane	-1.145
	1879.8	XY plane	-3.745
		YZ plane	-4.131
		XZ plane	-1.430

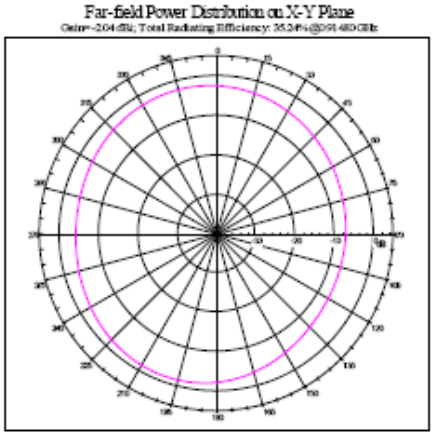
GSM1900

Frequency (GHz)		Plane	Average Gain (dBi)
TX	1850.2	XY plane	-3.511
		YZ plane	-4.649
		XZ plane	-1.147
	1880.0	XY plane	-3.746
		YZ plane	-4.124
		XZ plane	-1.435
	1909.8	XY plane	-4.683
		YZ plane	-4.228
		XZ plane	-2.525
RX	1930.2	XY plane	-5.539
		YZ plane	-4.270
		XZ plane	-3.257
	1960.0	XY plane	-6.444
		YZ plane	-4.441
		XZ plane	-4.126
	1989.8	XY plane	-8.068
		YZ plane	-5.359
		XZ plane	-5.477

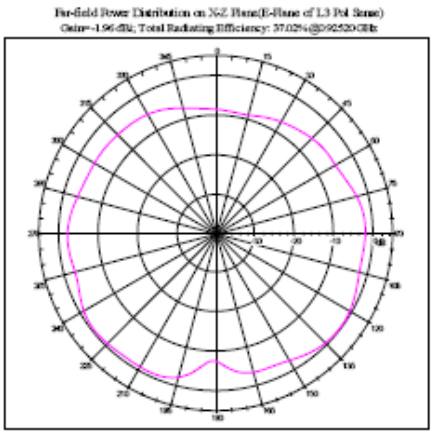
Frequency :914.8MHz

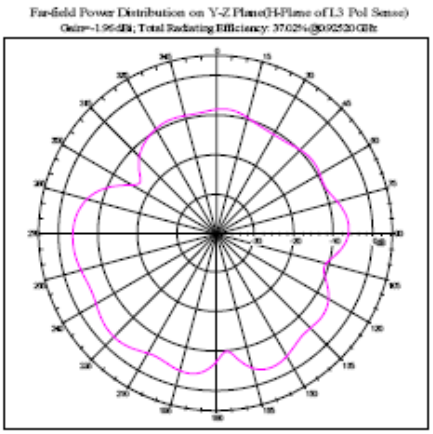


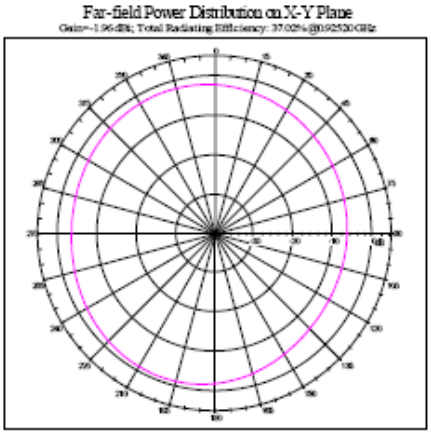




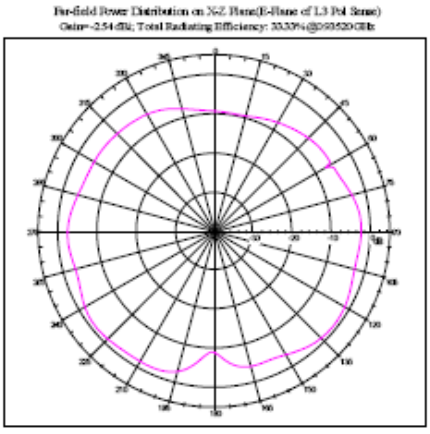
Frequency :925.2MHz

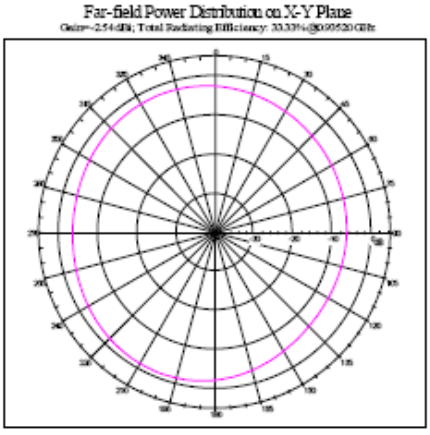


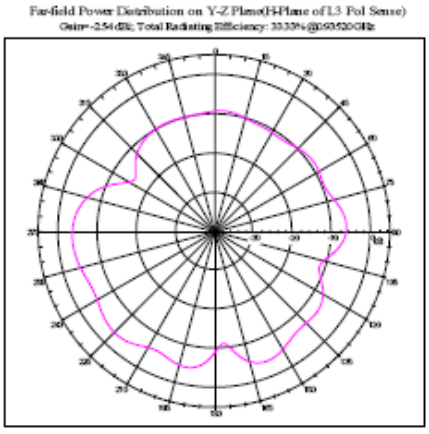




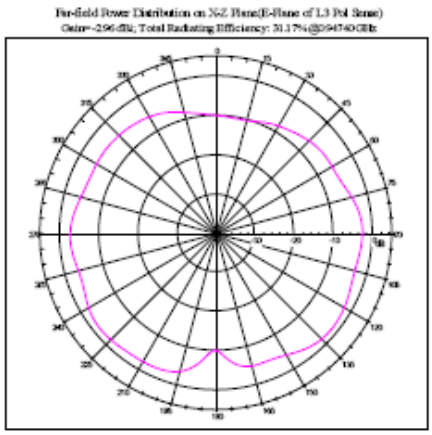
Frequency :935.2MHz

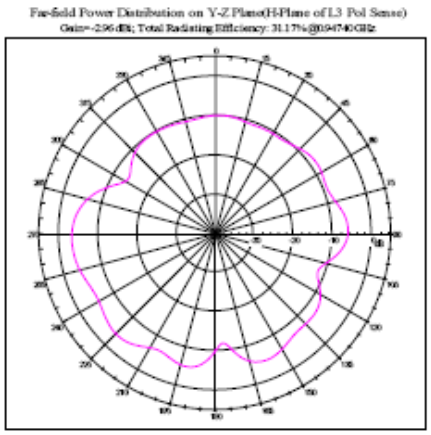


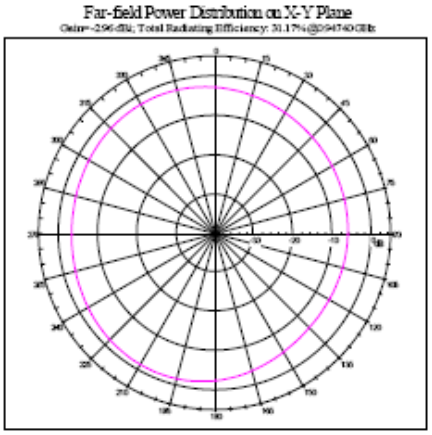




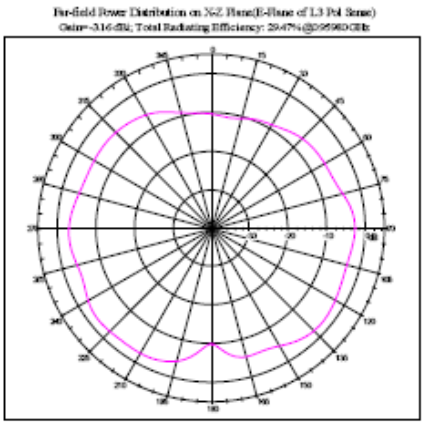
Frequency :947.4MHz

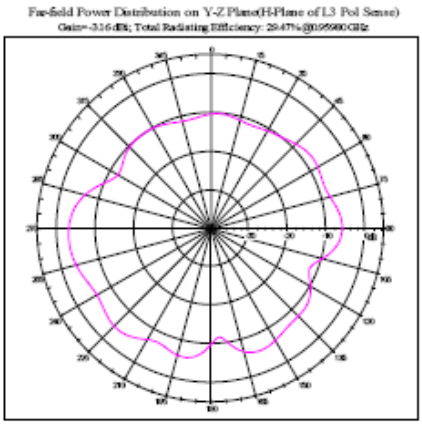


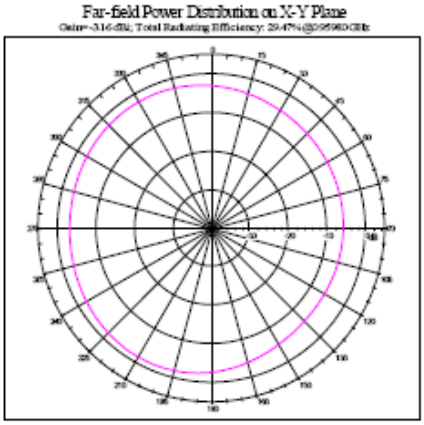




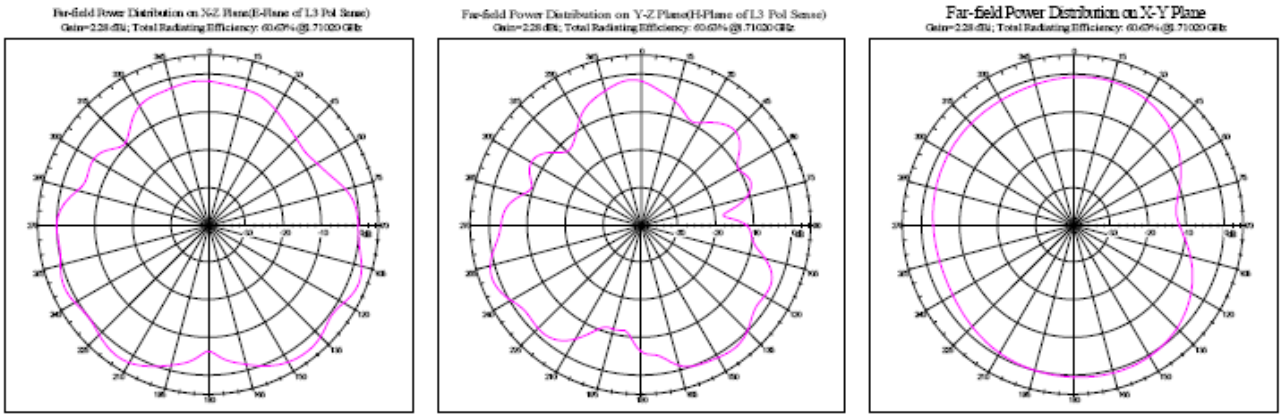
Frequency :959.8MHz



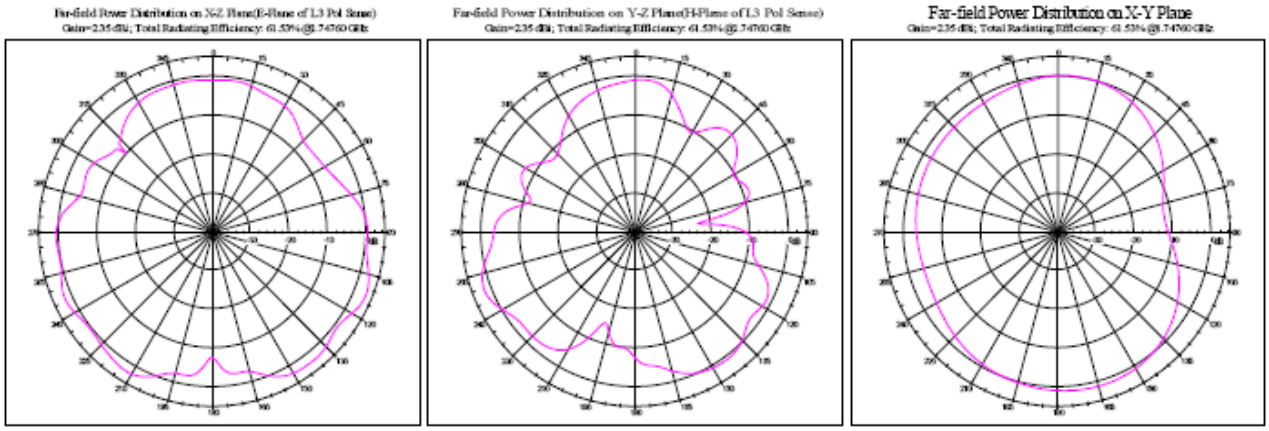




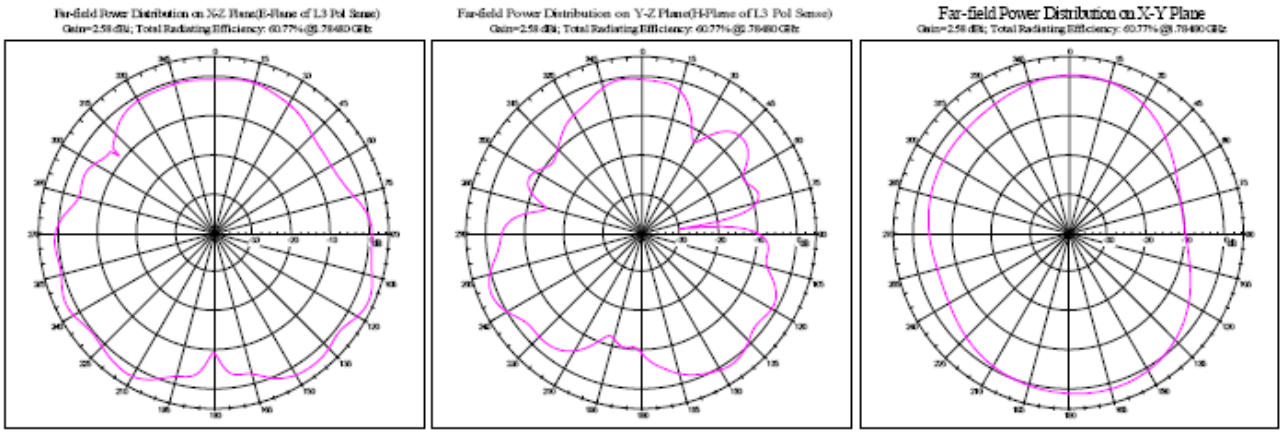
GSM1800
Frequency :1710.2 MHz



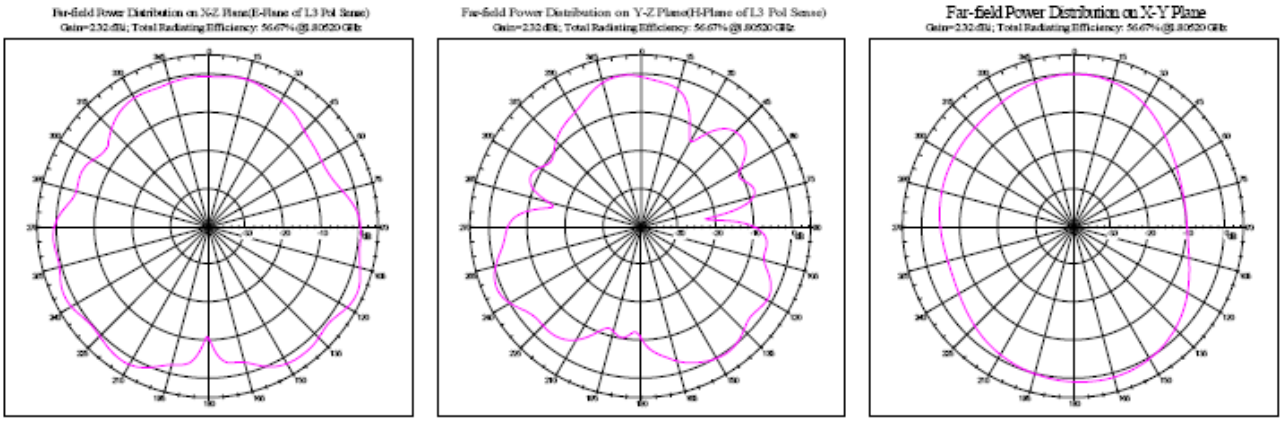
Frequency :1747.6 MHz



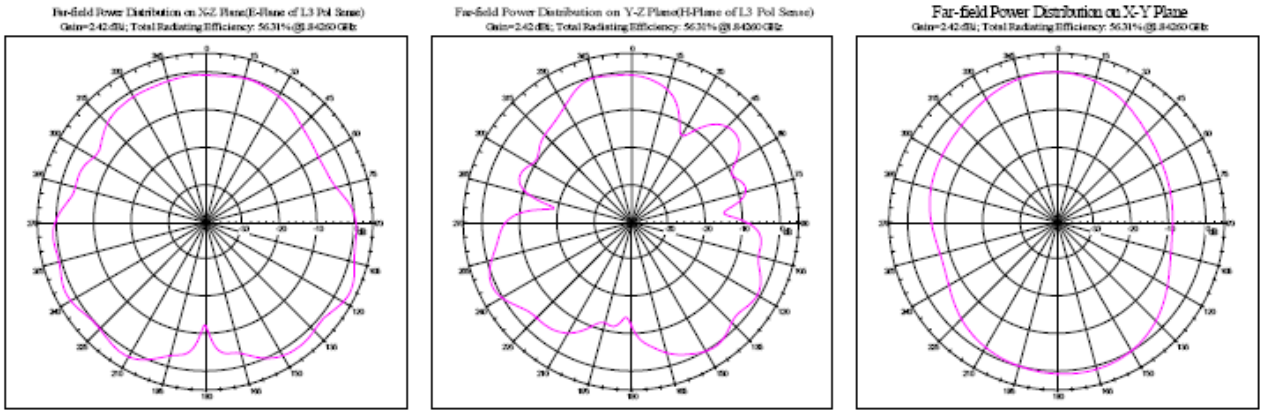
Frequency :1784.8 MHz



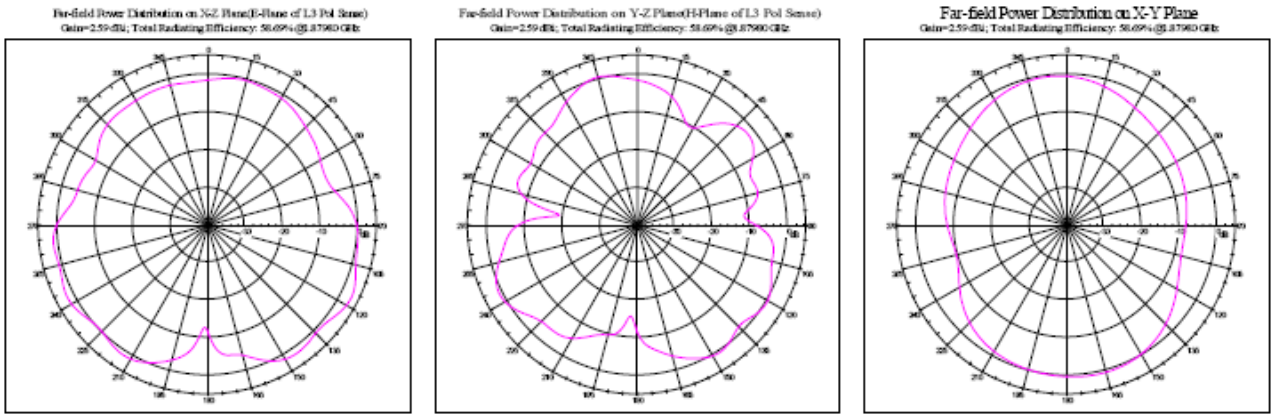
Frequency :1805.2 MHz



Frequency :1842.6 MHz

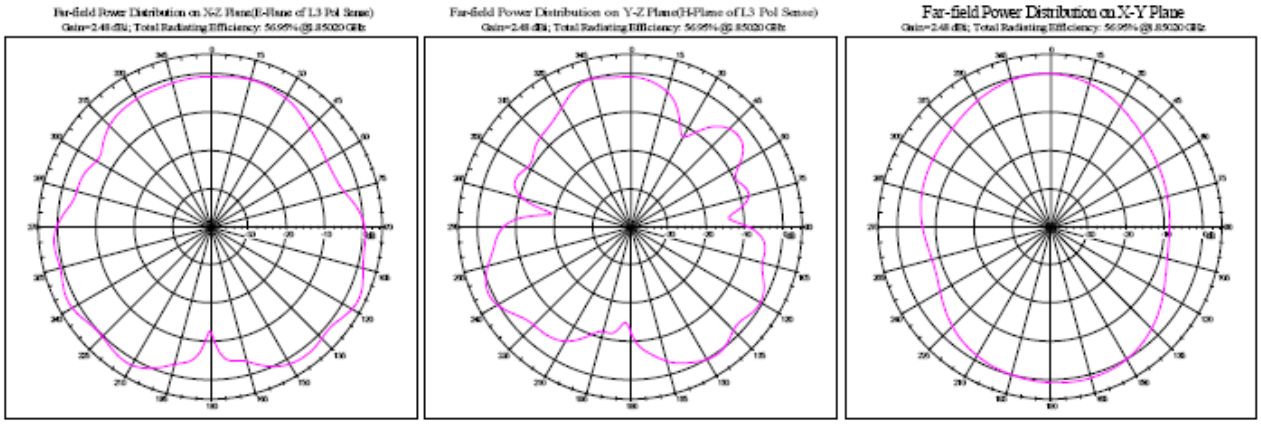


Frequency :1879.8 MHz

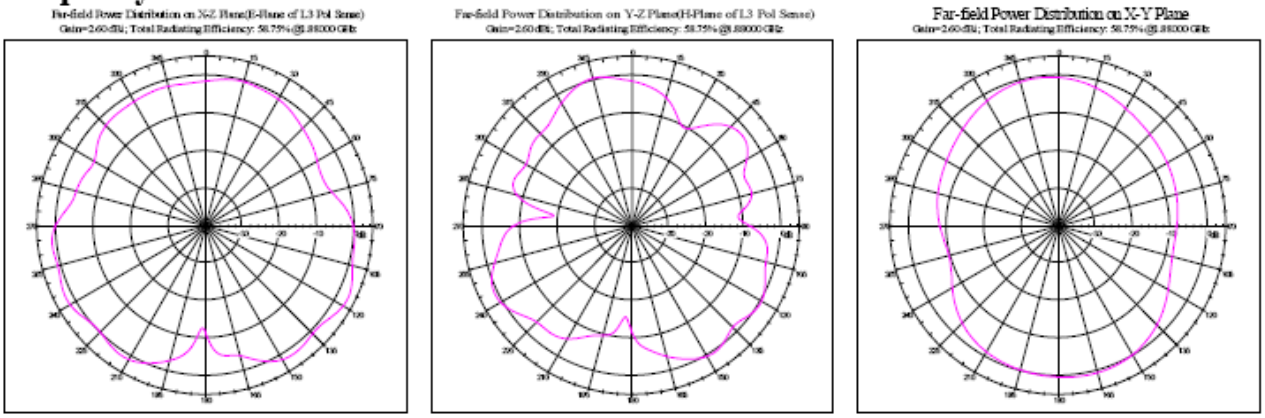


GSM1900

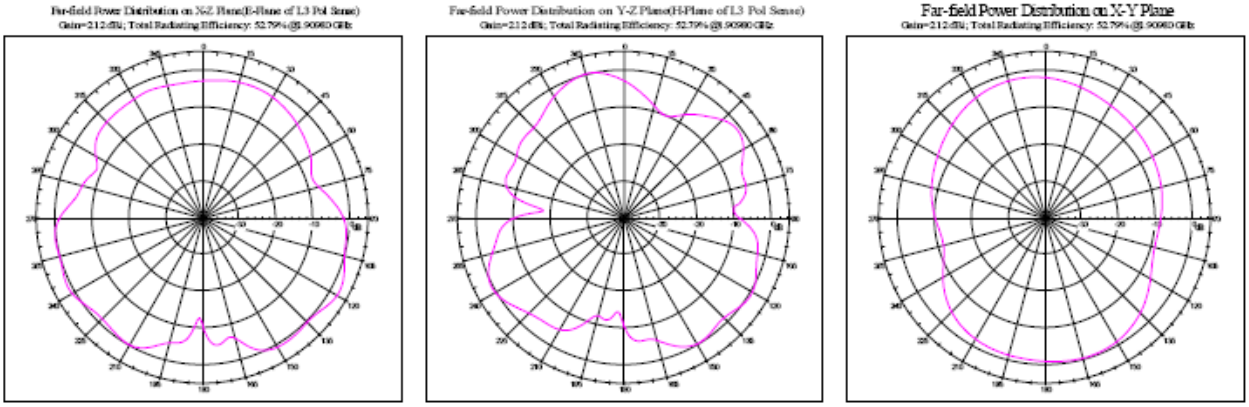
Frequency :1850.2 MHz



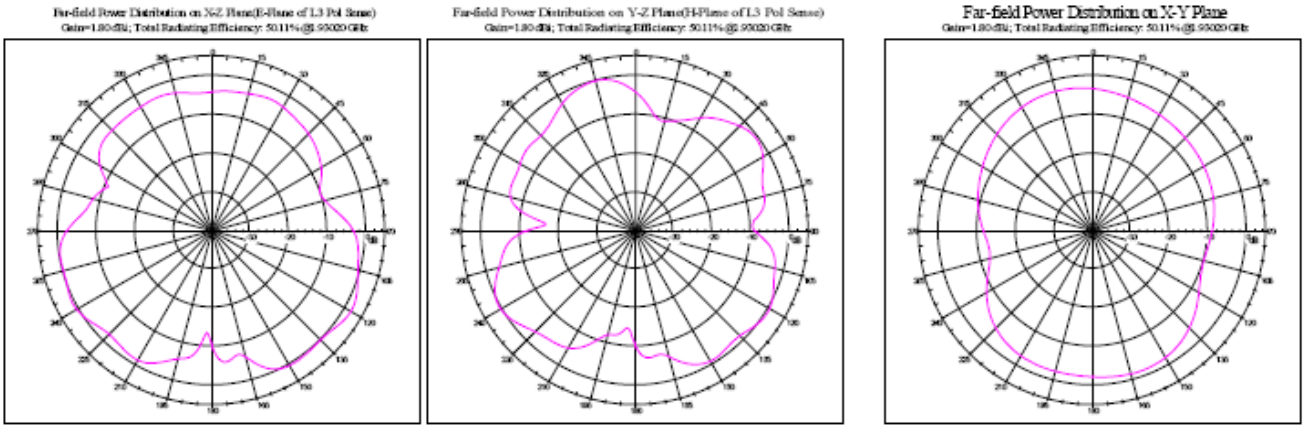
Frequency :1880.0 MHz



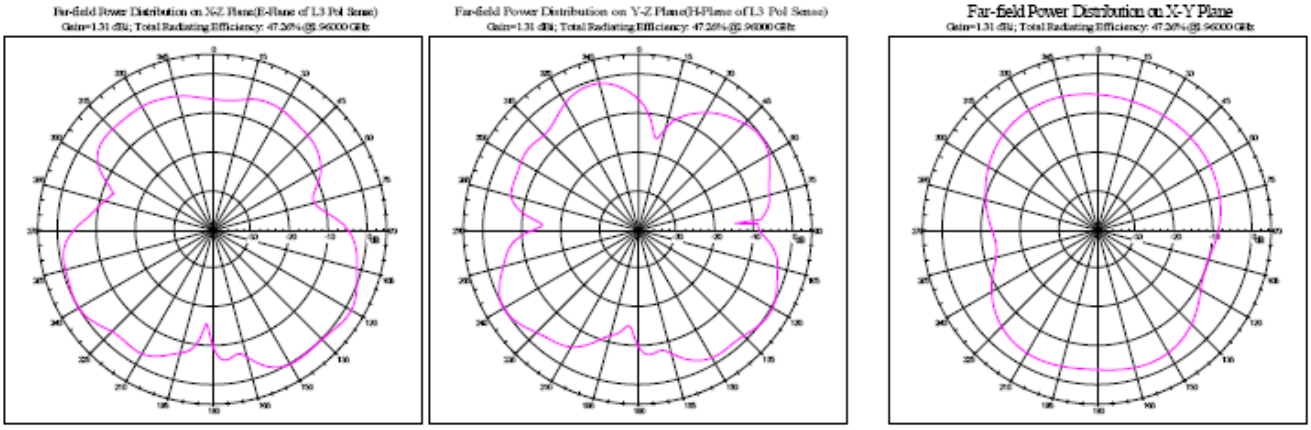
Frequency :1909.8 MHz



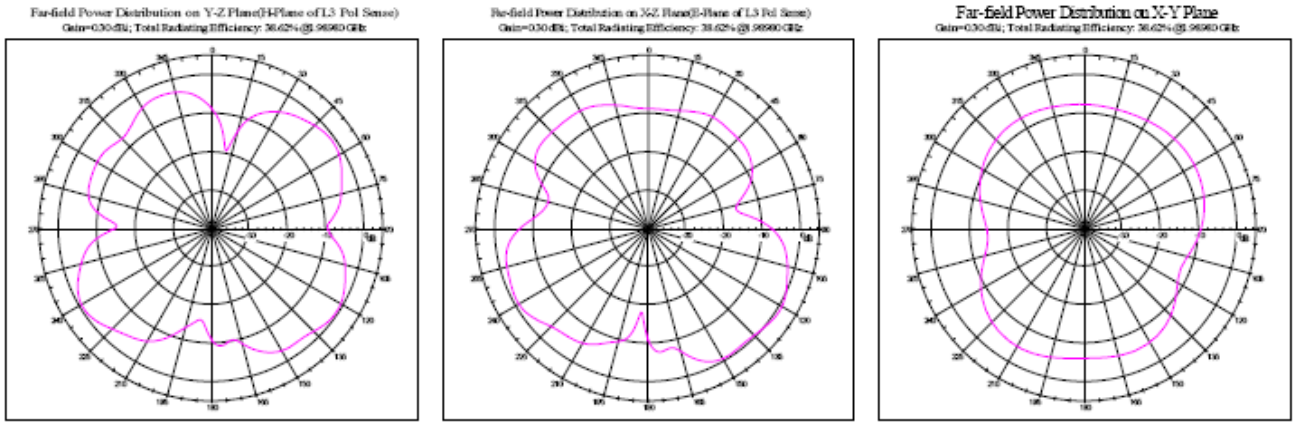
Frequency : 1930.2 MHz



Frequency : 1960.0 MHz

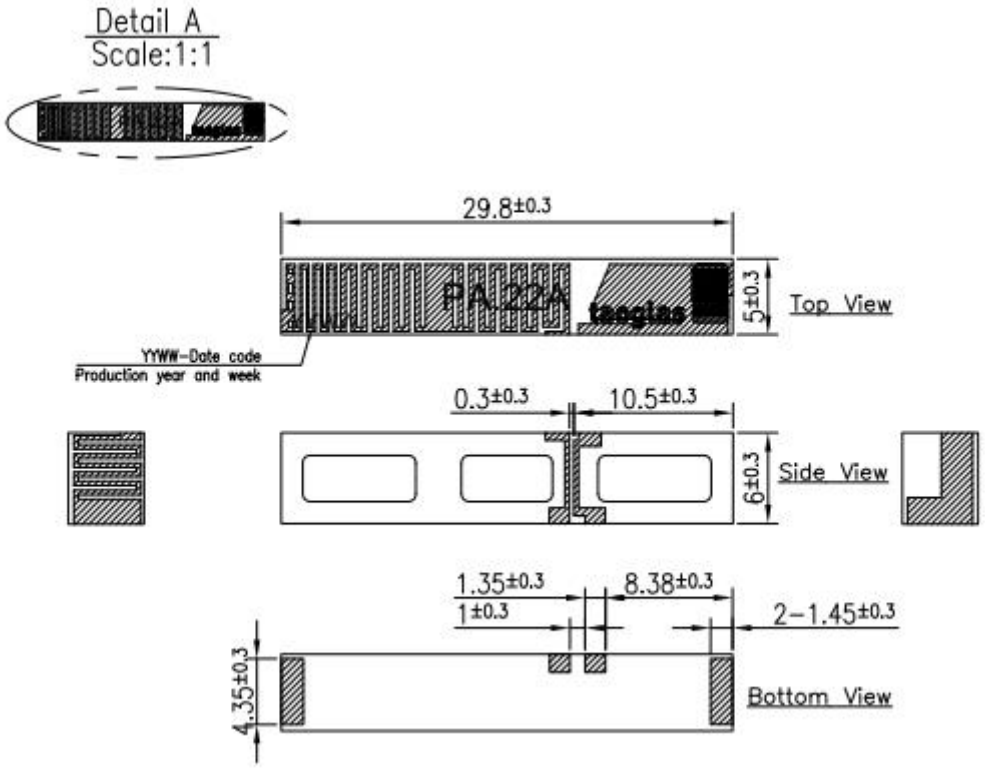


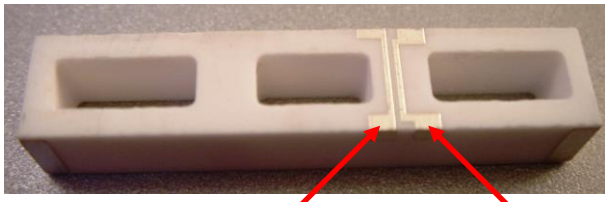
Frequency : 1989.8 MHz



3. Mechanical Dimensions

3.1. PA.22 Antenna



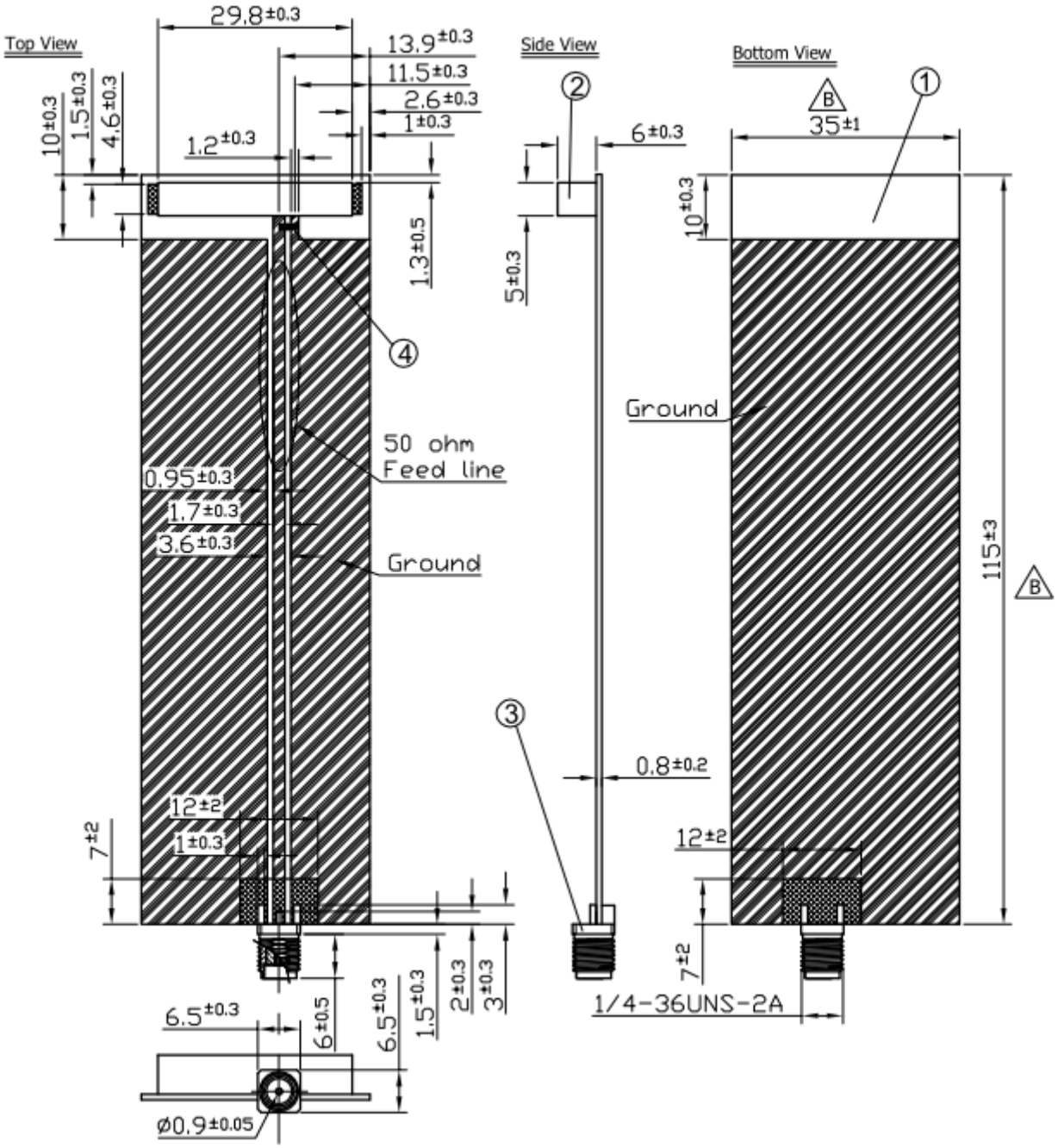


Feed to Module

To Ground

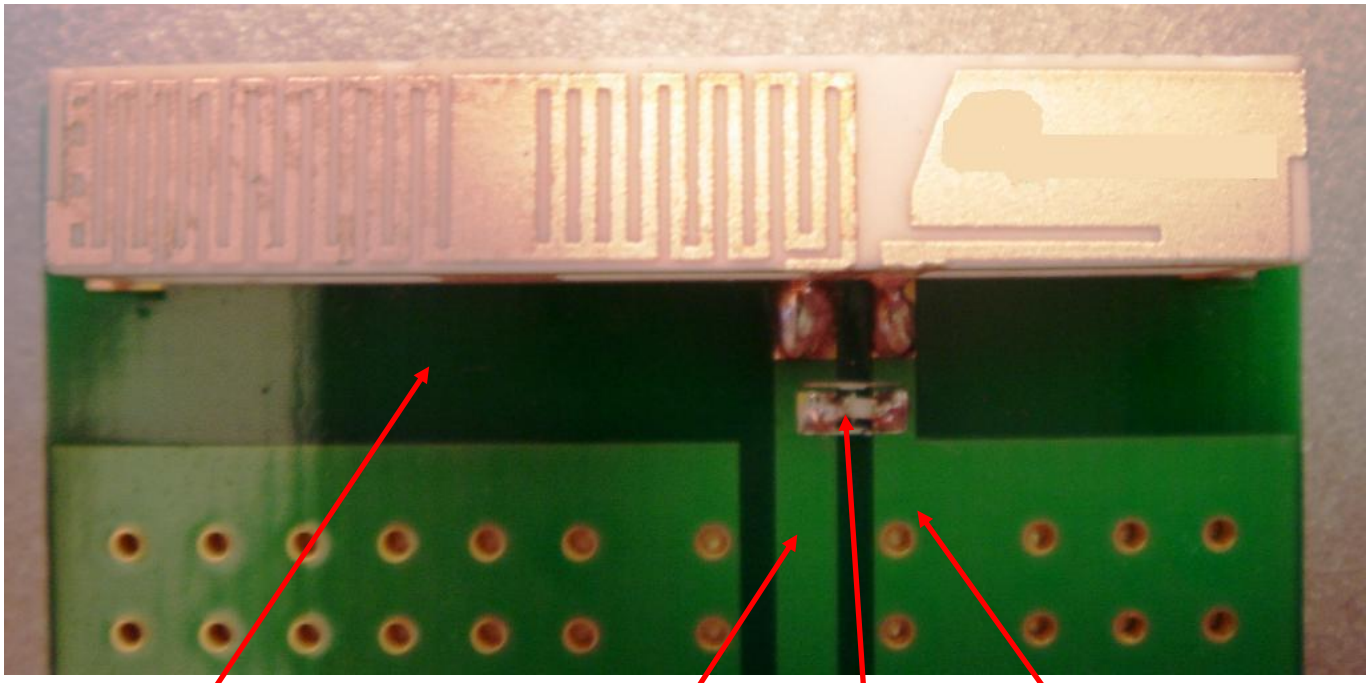
Solder Pads
(Mechanical Only)

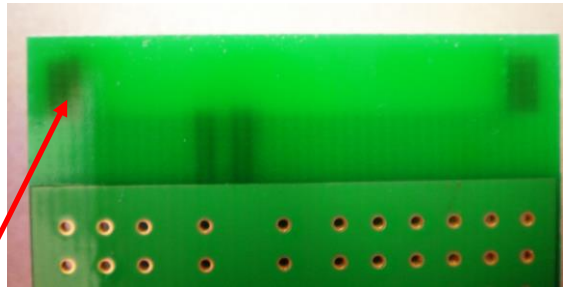
3.2. Evaluation Board Dimensions



Note:
1.Unique dimensioning according to your PCB
inductor and capacitor values according to you specific device
2.Copper area
3.Soldered area
4.Clearance area

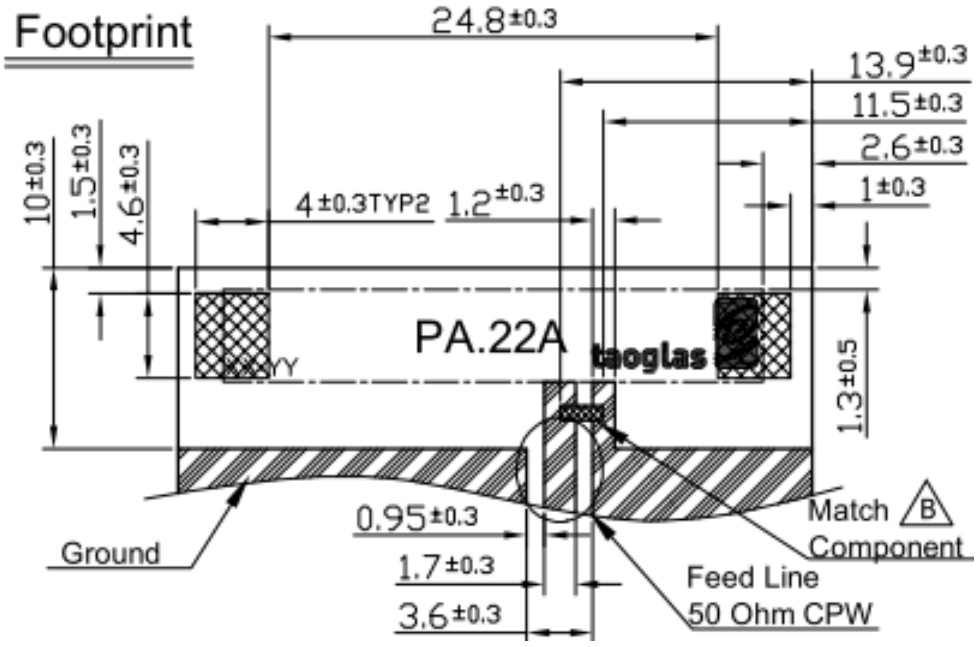
3.3. Recommended Layout (As Per Taoglas Evaluation Board)



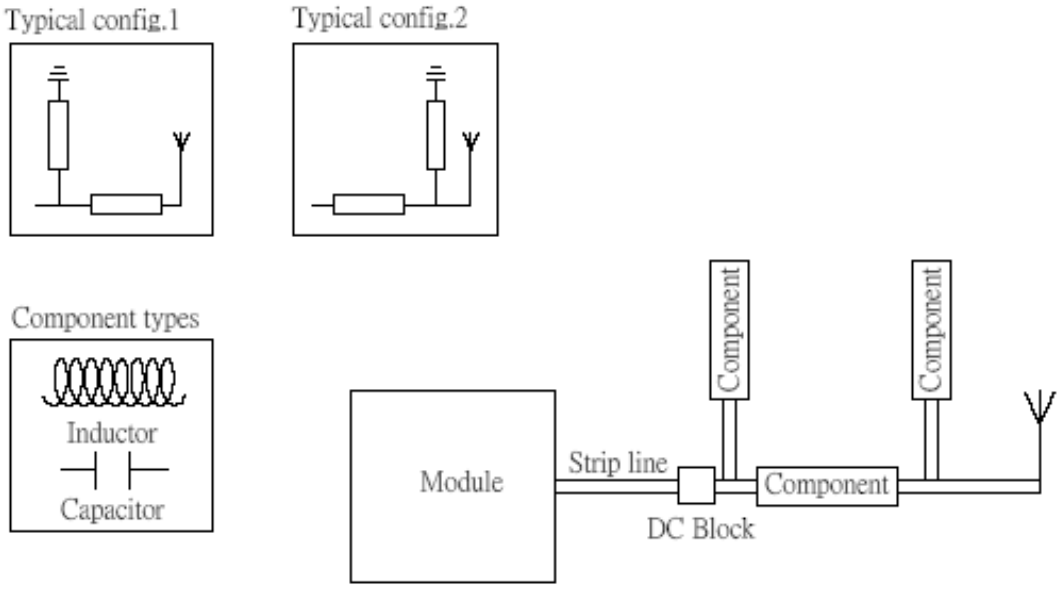


View from underneath board – note solder pads either side – laid out on non metal area

Layout dimensions - Allow 6mm clearance all around if possible (minimum 4mm)


Footprint
24.8±0.3
13.9±0.3
11.5±0.3
2.6±0.3
1±0.3
10±0.3
1.5±0.3
4.6±0.3
4±0.3TYP2
1.2±0.3
PA.22A
taoglas
YYWW
1.3±0.5
Match
B
Component
Ground
0.95±0.3
1.7±0.3
3.6±0.3
Feed Line
50 Ohm CPW

3.4. Recommended Transmission Line and Matching Network

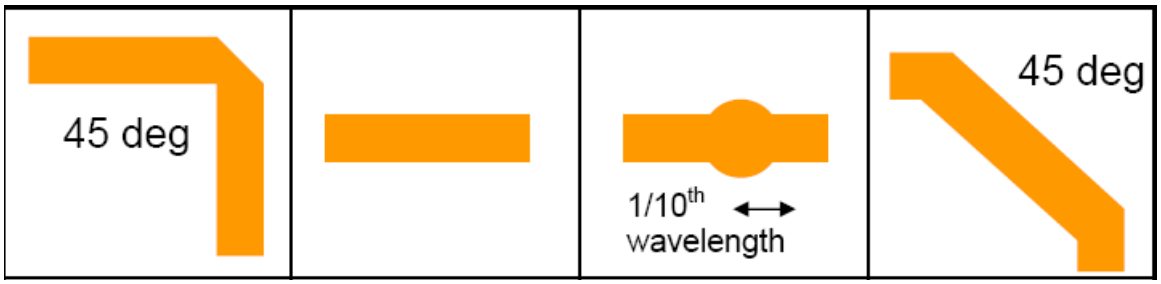


The matching network has to be individually designed using one,two or three components.

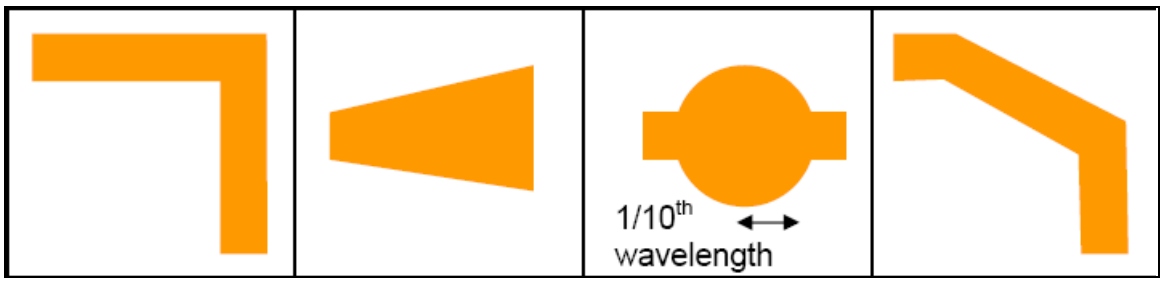
Note: The PA.22 can be made "quad band" with appropriate matching circuit

Guidelines for routing RF when designing a PCB;

1) Good

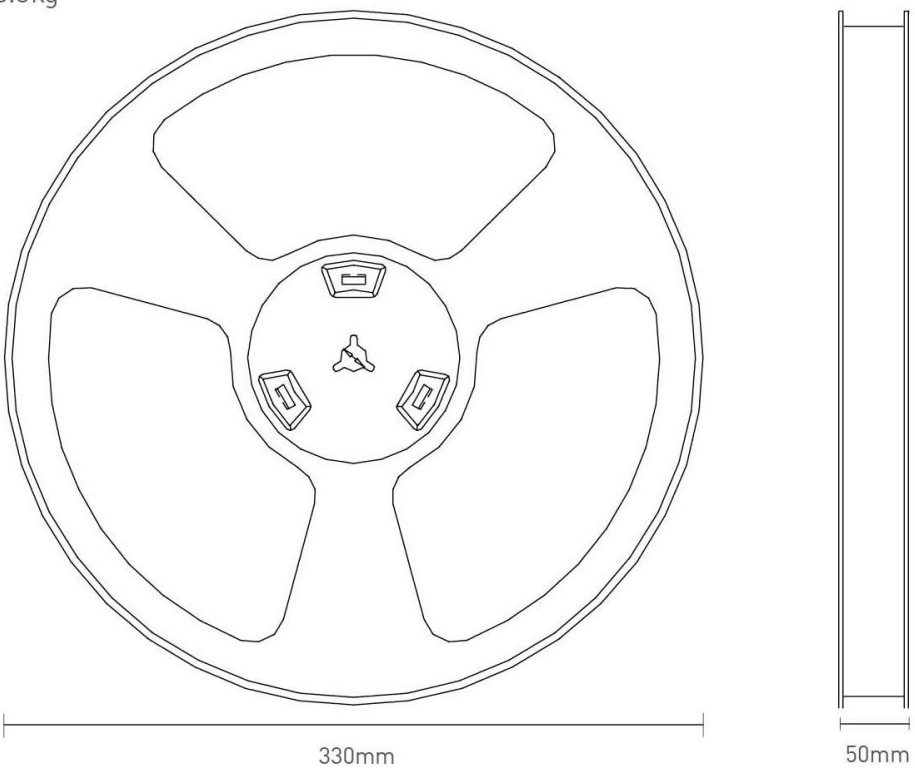


2) Bad

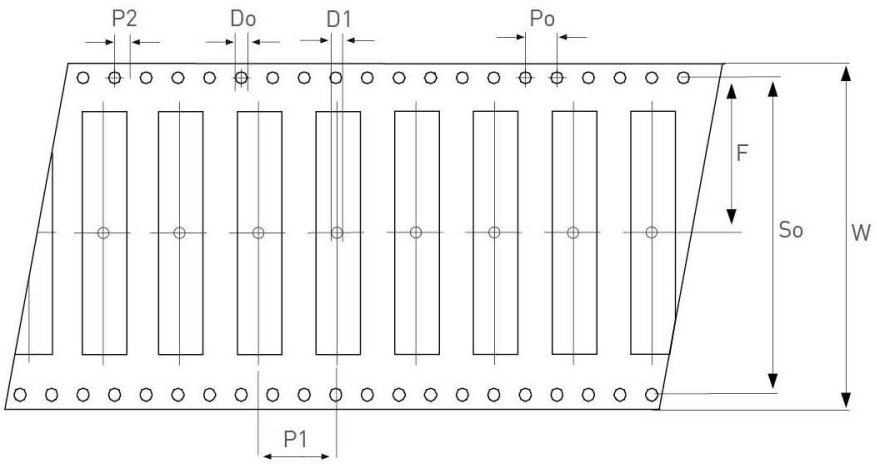


4. Packaging

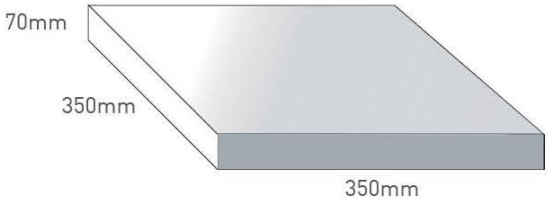
450 pc PA.22.A
1 reel per small inner box
Dimensions - 330*50mm
Weight - 3.3kg



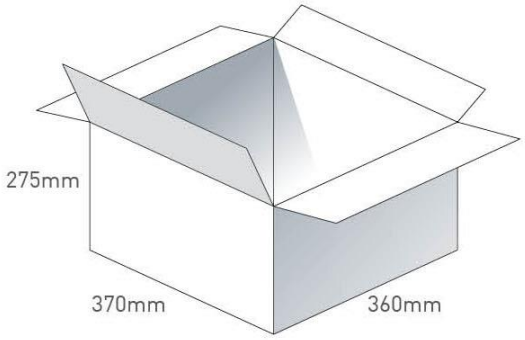
Symbol	Spec
Po	4.0 ± 0.10
P1	12.0 ± 0.10
P2	2.0 ± 0.15
Do	1.5
D1	2.0 (Min)
F	20.2 ± 0.10
So	40.4 ± 0.10
W	44.0 ± 0.30



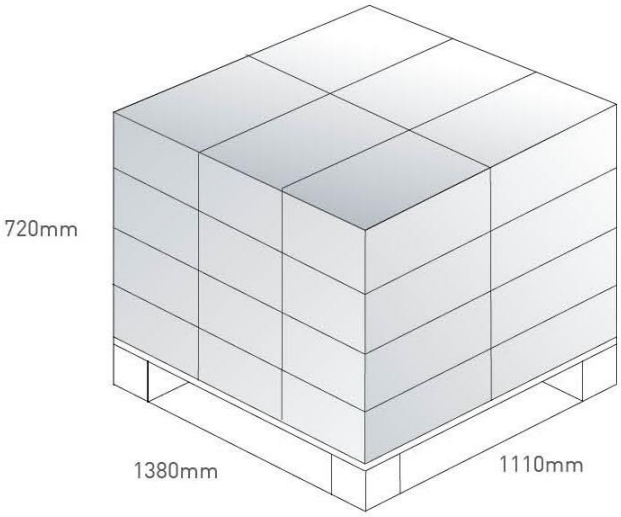
450 pc PA.22.A
1 reel in small inner box
Dimensions - 350*350*70
Weight - 3.6Kg



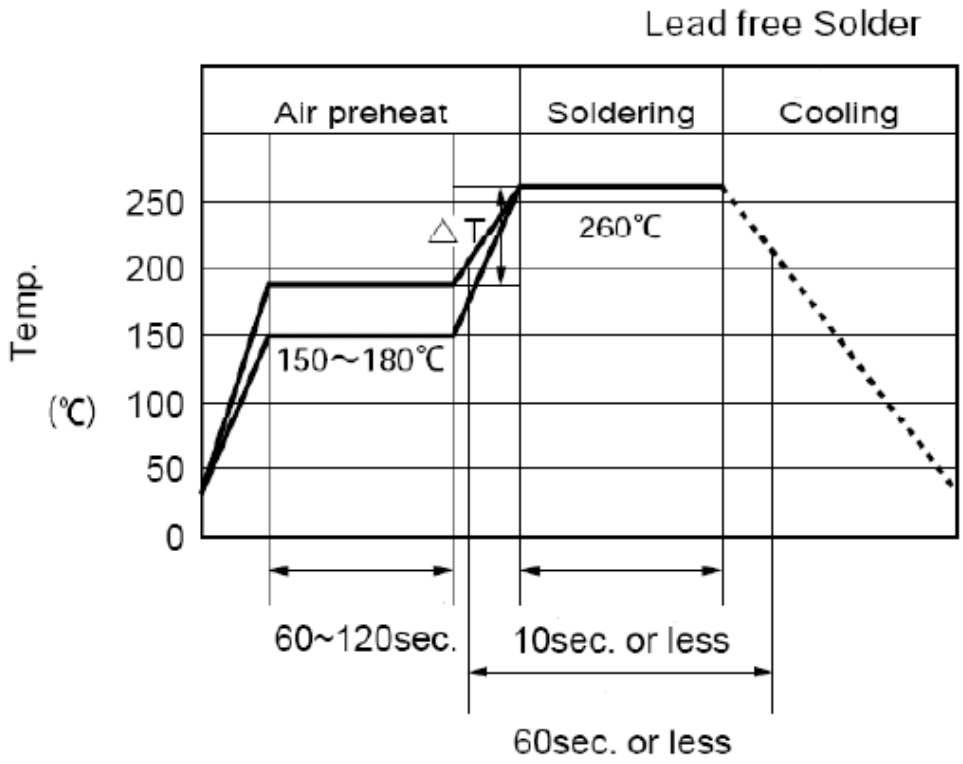
4 boxes / 1800 pcs in one carton
Carton Dimensions - 370*360*275mm
Weight -14.4Kg



Pallet Dimensions 1110*720*1380mm
24 Cartons per Pallet
6 Cartons per layer
4 Layers



5. Recommended Reflow Temperature Profile



(1) Time shown in the above figures is measured from the point when chip surface reaches temperature.

(2) Temperature difference in high temperature part should be within 110°C.

(3) After soldering, do not force cool, allow the parts to cool gradually.

*General attention to soldering:

• High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.

• for soldering, please refer to the soldering curves above. However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.

● Please use a mild flux (containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that **could affect resistance.**

Cleaning:

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40 kHz max. - Output power: 20W/Iiter -Cleaning time: 5 minutes max.